Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	1.6 X 1.6 X 0.55 (1.05X0.5 EP)
Lead Count	6
Terminal Finish	NiPdAu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.65E-03	83.25	832500	29.17	291746
Thermosets	Epoxy resin	Proprietary	1.72E-04	5.42	54200	1.90	18994
Thermosets	Phenol resin	Proprietary	1.10E-04	3.45	34500	1.21	12090
Other inorganic materials	Metal Hydroxide	Proprietary	1.72E-04	5.42	54200	1.90	18994
Others	Others	Proprietary	7.82E-05	2.46	24600	0.86	8621
Subtotal			3.18E-03	100.00	1000000	35.04	350446

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.35 E-03	96.20	962000	36.87	368674
Copper & its alloys	Nickel	7440-02-0	1.04 E-04	3.00	30000	1.15	11497
Copper & its alloys	Silicon	7440-21-3	2.26 E-05	0.65	6500	0.25	2491
Copper & its alloys	Magnesium	7439-95-4	5.22 E-06	0.15	1500	0.06	575
Subtotal			3.48 E-03	100.00	1000000	38.32	383237

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	2.95 E-05	87.5	875000	0.33	3250
Precious metals	Palladium	7440-05-3	3.86 E-06	11.5	114600	0.04	426
Precious metals	Gold	7440-57-5	3.51 E-07	1.0	10400	0.00	39
Subtotal			3.37 E-05	100.00	1000000	0.37	3715

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.77 E-05	100.0	1000000	1.08	10762

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.27 E-03	100.0	1000000	25.05	250518

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.24 E-06	77.00	770000	0.10	1018
Other organic materials	Acrylic resin	Proprietary	8.40 E-07	7.00	70000	0.01	93
Other organic materials	Acrylate	Proprietary	6.60 E-07	5.50	55000	0.01	73
Other organic materials	Polybutadiene derivative	Proprietary	5.40 E-07	4.50	45000	0.01	60
Thermoset	Epoxy resin	Proprietary	3.00 E-07	2.50	25000	0.00	33
Other organic materials	Butadiene Copolymer	Proprietary	1.80 E-07	1.50	15000	0.00	20
Others	Additive	Proprietary	1.80 E-07	1.50	15000	0.00	20
Others	Peroxide	Proprietary	6.00 E-08	0.50	5000	0.00	7
Subtotal			1.20 E-05	100.0	1000000	0.13	1323

	Weight (g)	Percentage (%)	PPM
Package Totals	**9.08 E-03**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ANALOG DEVICES